NOTES, UNLESS OTHERWISE SPECIFIED:

1. RESISTANCE VALUES IN OHMS.

2. CAPACITANCE VALUES IN MICROFARADS.

3. REFERENCE DESIGNATORS USED:

4. ALL .1 uF AND .01uF CAPACITORS ARE DECOUPLING CAPS UNLESS OTHERWISE NOTED. THEY ARE SHOWN ON THE PAGE WITH THE INTEGRATED CIRCUITS THEY SHOULD BE PLACED NEAR.

SCHEMATIC CONTENTS
01 - TITLE PAGE
02 - TMS320C5535 IO
03 - UART BUFFER
04 - TMS320C5535 POWER
05 - SPI FLASH
06 - CC BOARD INTERFACE
07 - MICRO SD INTERFACE
08 - POWER SUPPLIES
09 - AUDIO CODEC
10 - LCD/USER LEDS/SWITCHES
11 - EXPANSION CONNECTOR
12 - XDS100-v2 INTERFACE
NOTE: DIMENSIONS AND LOCATIONS OF THESE CONNECTORS MUST MEET SPECIFICATION FOR INTERFACE MODULES
Vout = Vref \times (1 + \frac{R_{top}}{R_{Bottom}}); \quad V_{REF} = 0.6
Vout = 0.6 \times (1 + 2)

Vout = Vref \times (1 + \frac{R_{top}}{R_{Bottom}}); \quad V_{REF} = 0.6
Vout = 0.6 \times (1 + 4.47)
RF1 = \((\text{Vout}/\text{Vref} - 1)\) * RF2
RF1 = \((1.3/1.224 - 1)\) * 169K

R125
10.7K

C95
4.7uF

R126
169K 1%

C26
4.7uF

R127
220K

TP7
VCC_IV0_TP

TARGET_PWR_GOOD 2,10,11,13

Power Monitor I2C Probe Point Headers
STEREO IN 1

HEADPHONES OUT

I2C ADDRESS
001 1000

Select Internal LDO

Tie Analog Power to Digital Power through single point connection or Ferrite Bead.
TMS320C5535 EZDSP MODULE
LCD INTERFACE
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